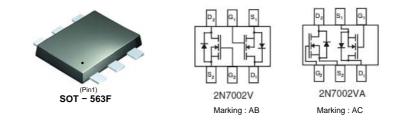


2N7002V/VA N-Channel Enhancement Mode Field Effect Transistor

Features

- Dual N-Channel MOSFET
- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- Lead Free By Design/RoHS Compliant



Absolute Maximum Ratings * T_a = 25°C unless otherwise noted

Symbol	Parameter		Value	Units
V _{DSS}	Drain-Source Voltage		60	V
V _{DGR}	Drain-Gate Voltage $R_{GS} \le 1.0M\Omega$		60	V
V _{GSS}	Gate-Source Voltage	Continuous Pulsed	±20 ±40	V
I _D	Drain Current	Continuous Pulsed	280 1.5	mA A
T _J , T _{STG}	Junction and Storage Temperature Range		-55 to +150	°C

* These ratings are limiting values above which the serviceability of any semiconductor device may by impaired.

Thermal Characteristics

Symbol	Parameter	Value	Units
P _D	Total Device Dissipation Derating above TA = 25°C	250 2.0	mW mW/°C
R_{\thetaJA}	Thermal Resistance, Junction to Ambient *	500	°C/W

* Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch. Minimun land pad size,

October 2007

Symbol	Parameter	Test Condition	MIN	TYP	MAX	Units
Off Charac	teristics (Note1)					
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D =10uA	60	78	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 60V, V_{GS} = 0V V_{DS} = 60V, V_{GS} = 0V, @T _C = 125°C	-	0.001 7	1.0 500	uA
I _{GSS}	Gate-Body Leakage	V_{GS} = ±20V, V_{DS} = 0V	-	0.2	±100	nA
On Charac	teristics (Note1)					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250 uA$	1.0	1.76	2.5	V
R _{DS(ON)}	Satic Drain-Source On-Resistance	$V_{GS} = 5V, I_D = 0.05A,$ $V_{GS} = 10V, I_D = 0.5A, T_j = 125^{\circ}C$	-	1.6 2.53	7.5 13.5	Ω
I _{D(ON)}	On-State Drain Current	V _{GS} = 10V, V _{DS} = 7.5V	0.5	1.43	-	А
9 FS	Forward Transconductance	$V_{DS} = 10V, I_D = 0.2A$	80	356.5	-	mS
Dynamic (Characteristics					
C _{iss}	Input Capacitance		-	37.8	50	pF
C _{oss}	Output Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz	-	12.4	25	pF
C _{rss}	Reverse Transfer Capacitance		-	6.5	7.0	pF
Switching	Characteristics					
t _{D(ON)}	Turn-On Delay Time	$V_{DD} = 30V, I_{D} = 0.2A, V_{GEN} = 10V$	-	5.85	20	
t _{D(OFF)}	Turn-Off Delay Time	R _L = 150Ω, R _{GEN} = 25Ω	-	12.5	20	ns

Note1 : Short duration test pulse used to minimize self-heating effect.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

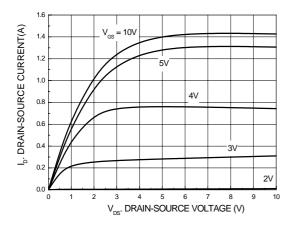


Figure 3. On-Resistance Variation with Temperature

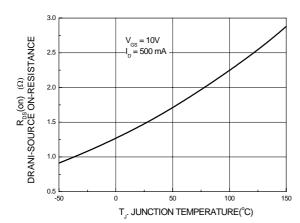


Figure 5. Transfer Characteristics

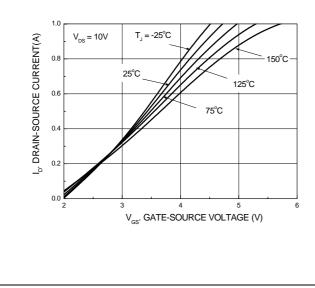


Figure 2. On-Resistance Variation with Gate Voltage and Drain Current

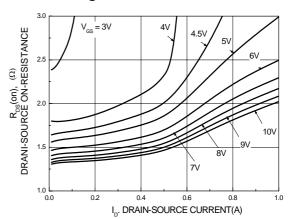
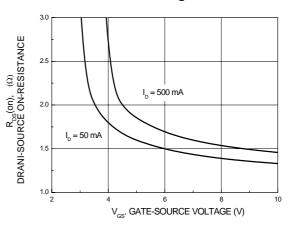
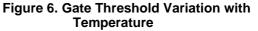
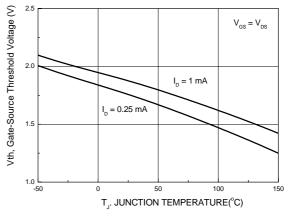
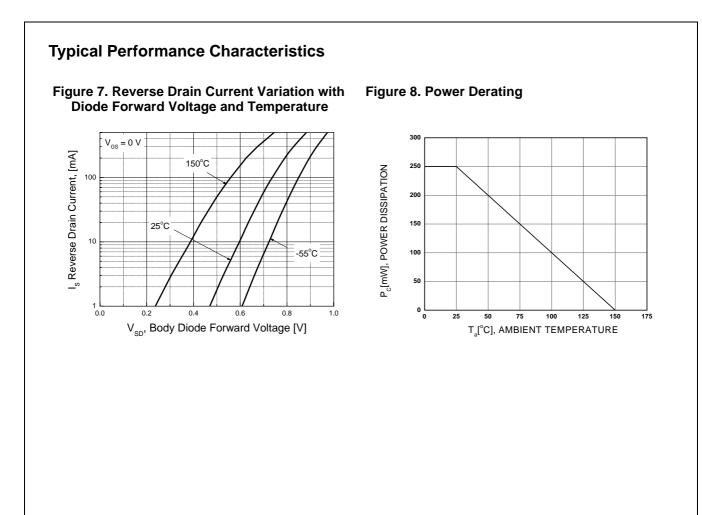


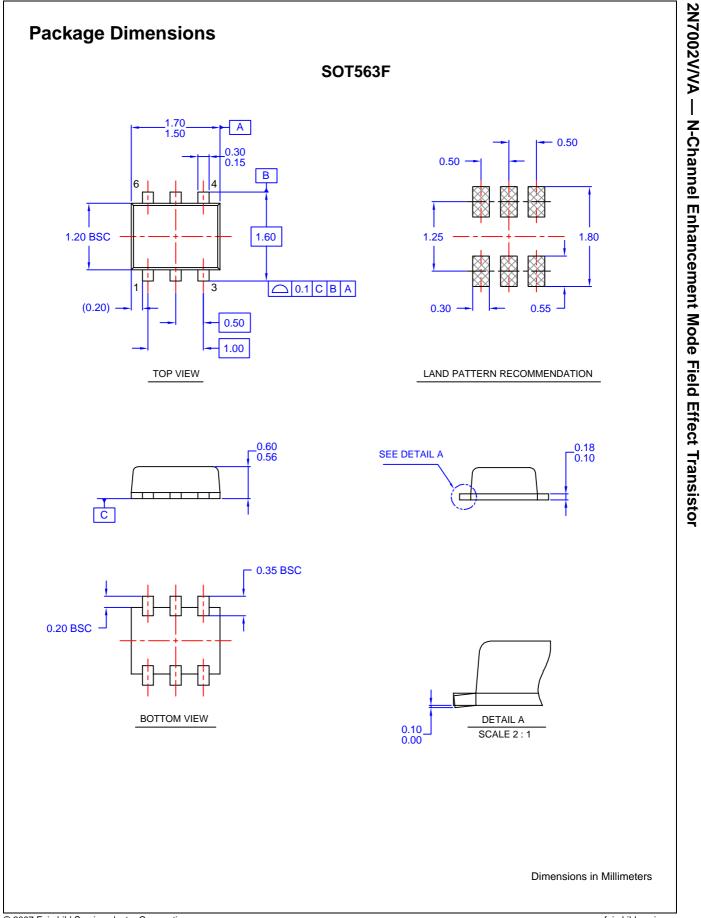
Figure 4. On-Resistance Variation with Gate-Source Voltage













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